

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention	ENCAPSULATED PIN STRUCTURE FOR IMPROVED RELIABILITY OF WAFER																																																						
<p>Application Number : Confirmation Number: First Named Applicant: Tien-Jen Cheng Attorney Docket Number: FIS920030103US1 Art Unit: Examiner: Search string: (5773889 or 5989935 or 6300236 or 6449840 or 6500324 or 20020179689).pn</p>																																																							
<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><i>W</i></td><td>1</td><td>5773889</td><td>1998-06-30</td><td>LOVE, ET AL.</td><td></td><td></td><td></td></tr><tr><td><i>N</i></td><td>2</td><td>5989935</td><td>1999-11-23</td><td>ABBOTT</td><td></td><td></td><td></td></tr><tr><td><i>AS</i></td><td>3</td><td>6300236</td><td>2001-10-09</td><td>HARPER, ET AL.</td><td></td><td></td><td></td></tr><tr><td><i>N</i></td><td>4</td><td>6449840</td><td>2002-09-17</td><td>LE, ET AL.</td><td></td><td></td><td></td></tr><tr><td><i>AS</i></td><td>5</td><td>6500324</td><td>2002-12-31</td><td>SIMPSON, ET AL.</td><td></td><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	<i>W</i>	1	5773889	1998-06-30	LOVE, ET AL.				<i>N</i>	2	5989935	1999-11-23	ABBOTT				<i>AS</i>	3	6300236	2001-10-09	HARPER, ET AL.				<i>N</i>	4	6449840	2002-09-17	LE, ET AL.				<i>AS</i>	5	6500324	2002-12-31	SIMPSON, ET AL.			
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